

AK58256AG / AK58256AS 262,144 x 8 bit CMOS Dynamic Random Access Memory

DESCRIPTION

The Accutek AK58256AG/AS high density memory modules is a random access memory organized in 256K x 8 bit words. The assembly consists of two 256K x 4 DRAMs in surface mount packages mounted to a printed circuit board. The module can be configured as a leadless 30 pad SIM or a leaded 30 pin SIP. This packaging approach provides a better than 6 to 1 density increase over standard DIP packaging.

The operation of the AK58256 is identical to two 256K x 4 DRAMs. The data input/output is brought out separately for each 256K x 4 device, with common RAS, CAS and WE control. The OE pins are tied to Vss which dictates the use of early-write cycles to prevent contention of D and Q. Since the Write-Enable (WE) signal must always go low before CAS in a write cycle, Read-Write and Read-Modify-Write operation is not possible.

FEATURES

- 256K x 8 bit organization
- Optional 30 Pad SIM (Single In-Line Module) or 30 Pin leaded SIP (Single In-Line Package)
- · JEDEC approved pinout
- Common CAS, RAS and WE control for eight DQ lines

Data In/Data Out

Address Inputs

Write Enable

5v Supply

No Connect

Ground

Column Address Strobe

Row Address Strobe

- Separate CAS control for one separate pair of D and Q lines
- 1024 refresh cycles/16ms, A₀ to A₈

- Power:
 - .99 Watt Max Active (60 nS)
- .88 Watt Max Active (70 nS)
- .77 Watt Max Active (80 nS)
- .65 Watt Max Active (100 nS)
- 11 mWatt standby (max)
- Operating free air temperature: 0⁰ to 70⁰C
- Upward compatible with AK581024, AK584096 and AK5816384
- Functionally and Pin compatible with AK48256
- Available with access times of 60 to 100 nS

PIN NOMENCLATURE

DQ1 - DQ8

Ao - As

CAS

RAS

WE

Vcc

Vss

NC

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Р	 ч.	AS		7-1	ч.		•	

A6

Α7

14

15

PIN S	SYMBOL	PIN #	SYNGOL
1	Vcc	16	DQ5
2	CAS	17	A8
3	DQ1	18	nc
4	A0	19	NC
5	A1	20	DQ6
6	DQ2	21	WE
7	A2	22	Vss
8	A3	23	DQ7
9	Vss	24	NC
10	DQ3	25	DQ8
11	A4	26	NC
12	A5	27	RAS
13	DQ4	28	NC

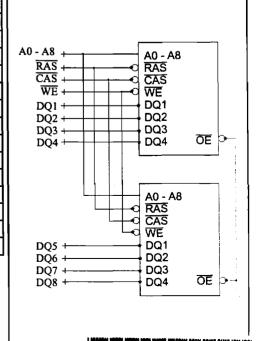
29

30

NC

Vcc

FUNCTIONAL DIAGRAM



MODULE OPTIONS

Leadless SIM: AK58256AS
Leadled SIP: AK58256AG

ORDERING INFORMATION

PART NUMBER CODING INTERPRETATION

Position

Product

AK = Accutek Memory

2 Type

> 4 = Dynamic RAM

5 = CMOS Dynamic RAM

= Static RAM

Organization/Word Width

1 = by 1 16 = by 16

4 = by 4 32 = by 32

8 = by 8 36 = by 36

9 = by 9

Size/Bits Depth

= 64K 64

4096 4 MEG =

256 = 256K 8192 = 8 MEG

1024 = 1 MEG 16384 **16 MEG**

Package Type

G = Single In-Line Package (SIP)

S = Single in-Line Module (SIM)

D = Dual In-Line Package (DIP)

W = .050 inch Pitch Edge Connect

Z = Zig-Zag in-Line Package (ZIP)

Special Designation

P = Page Mode

N = Nibble Mode

K = Static Column Mode

W = Write Per Bit Mode

V = Video Ram

7 Separator

- = Commercial 0°C to +70°C

M = Military Equivalent Screened

(-55°C to +125°C)

= Industrial Temperature Tested

(-45°C to +85°C)

X = Burned In

Speed (first two significant digits)

DRAMS SRAMS

 $60 = 60 \, \text{nS}$ $8 = 8 \, \text{nS}$

70 = 70 nS 12 = 12 nS

80 = 80 nS 15 = 15 nS

10 100 nS 20 = 20 nS

12 = 120 nS $70 = 70 \, \text{nS}$

= 150 nS 15 $85 = 85 \, \text{nS}$

The numbers and coding on this page do not include all variations available, but are shown as examples of the most widely used variations. Contact Accutek if other information is required.



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EXAMPLES:

AK58256ASP-60

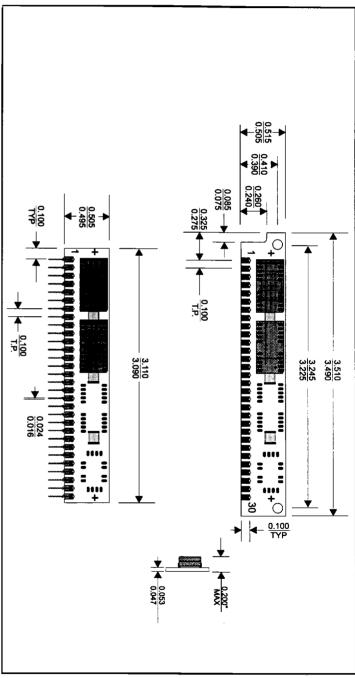
256K x 8, Dynamic RAM, Leadless SIM, Page Mode, Commercial, 60 nSEC Access Time

AK58256AGK-70

256K x 8, Dynamic RAM, Leaded SIP, Static Column Mode Commercial, 70 nSEC AccessTime

MECHANICAL DIMENSIONS

Inches



Accutek Reserves the right to make changes in specifications at any time and without notice. Accutek does not assume any responsibility for the use of any circuitry described; no circuit patent licenses are implied. Preliminary data sheets contain minimum and maximum limits based upon design objectives, which are subject to change upon full characterization over the specific operating conditions.